BGA Heat Sink - High Performance ASIC Cooling





ATS Part#: ATS-56001-C4-R0

Description: 19.00 x 19.00 x 9.00 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: ASIC Cooling
Heat Sink Attachment: Thermal Tape

Equivalent Part Number: N/A

*Image above is for illustration purpose only.

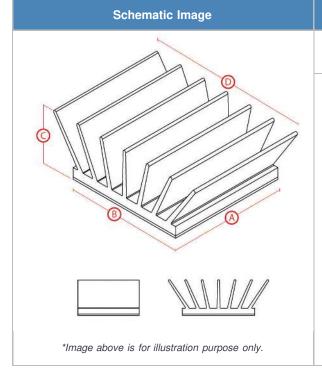
Features & Benefits

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- · Designed specifically for ASIC package and their unique cooling requirements

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	5.3 °C/W	4.1 °C/W	3.4 °C/W	3 °C/W	2.7 °C/W	2.4 °C/W	2.2 °C/W
	Ducted Flow	3.3	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail



Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
19.00 mm	19.00 mm	9.00 mm	26.3 mm	NO TIM	RED-ANODIZED

Notes:

- Dimension A and B refer to component size.
- Dimension C is the heat sink height from the bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.
- Contact ATS to learn about custom options available.

